

This diagram shows a cross-sectional view of a multi-layered electronic device assembly. The assembly consists of several layers and components, labeled with numbers 1 through 10. At the top, there is a layer labeled 1, which is a substrate or base layer. Below layer 1 is a layer labeled 2, which is a conductive layer. Below layer 2 is a layer labeled 3, which is a dielectric or insulating layer. Below layer 3 is a layer labeled 4, which is a conductive layer. Below layer 4 is a layer labeled 5, which is a dielectric or insulating layer. Below layer 5 is a layer labeled 6, which is a conductive layer. Below layer 6 is a layer labeled 7, which is a dielectric or insulating layer. Below layer 7 is a layer labeled 8, which is a conductive layer. Below layer 8 is a layer labeled 9, which is a dielectric or insulating layer. Below layer 9 is a layer labeled 10, which is a conductive layer. The assembly is shown in a cross-sectional view, with the layers and components arranged in a vertical stack. The layers are labeled with numbers 1 through 10, and the components are labeled with numbers 1 through 10. The assembly is shown in a cross-sectional view, with the layers and components arranged in a vertical stack.

*Fig. 2*

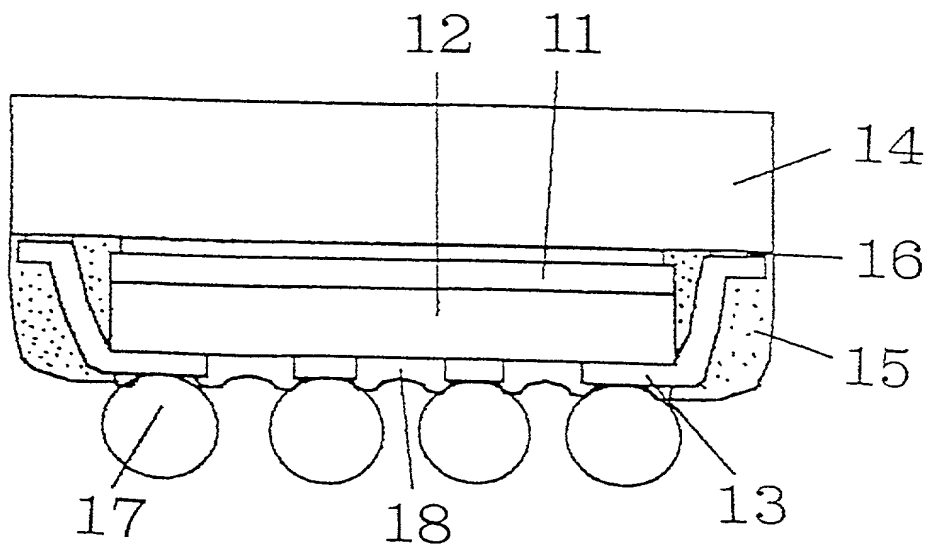
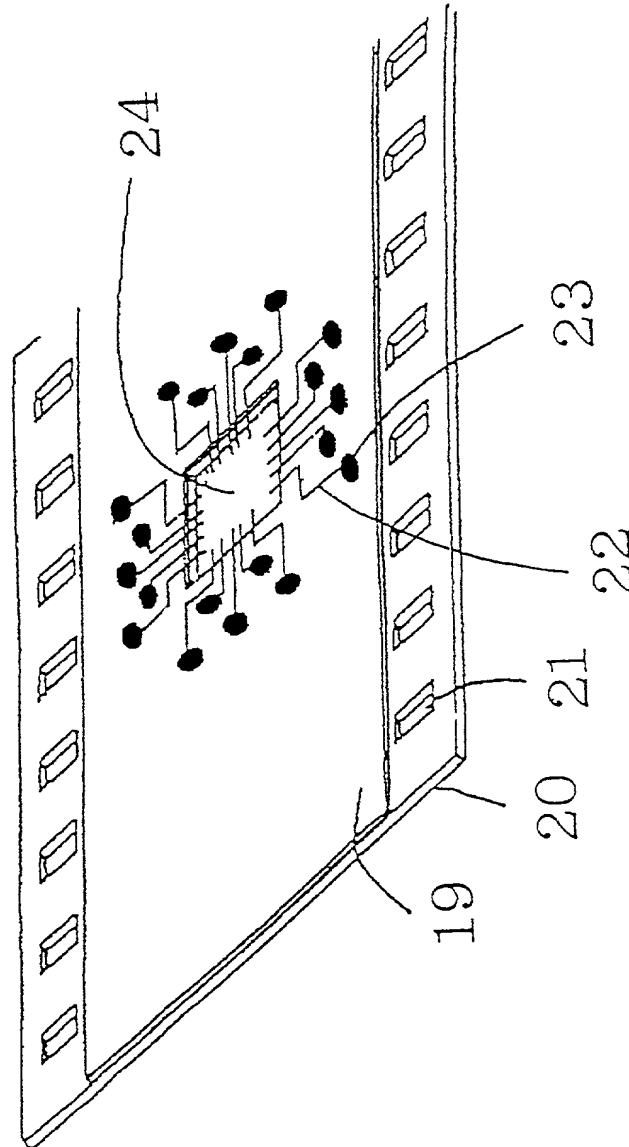


FIG. 2

Fig. 3



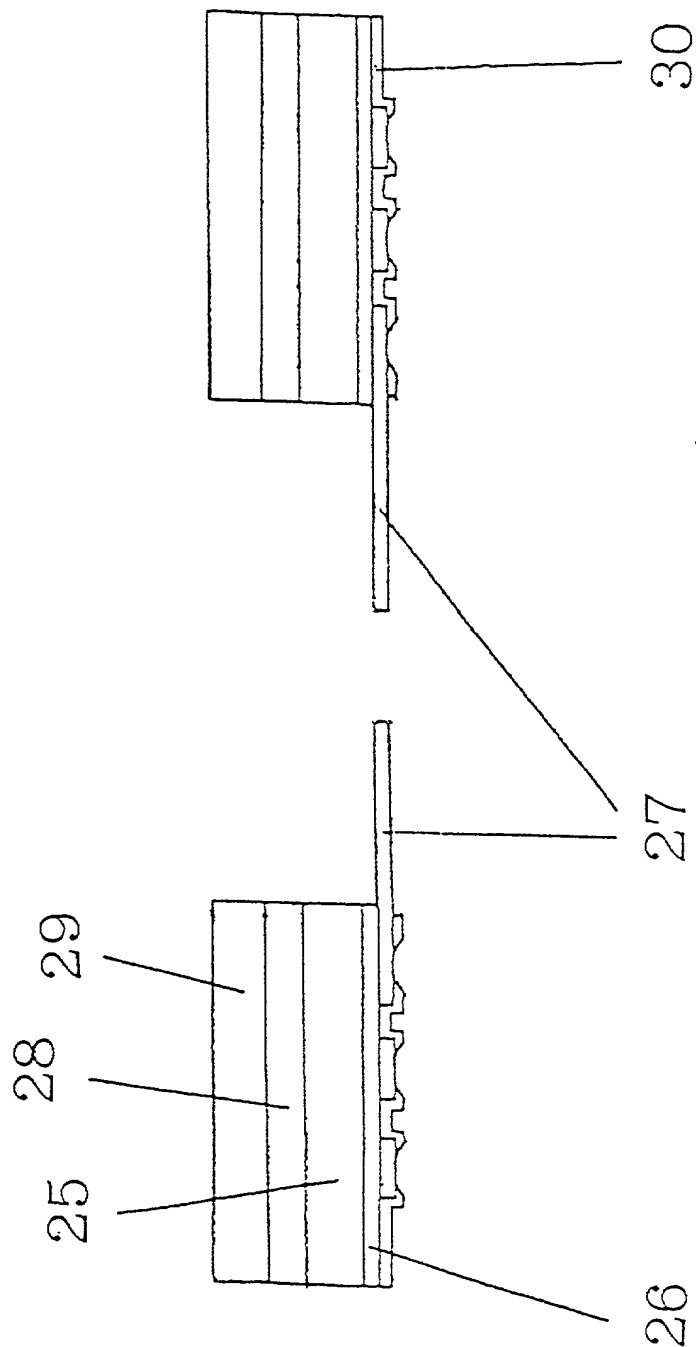


Fig. 4

T06220"ET504660

Fig. 5

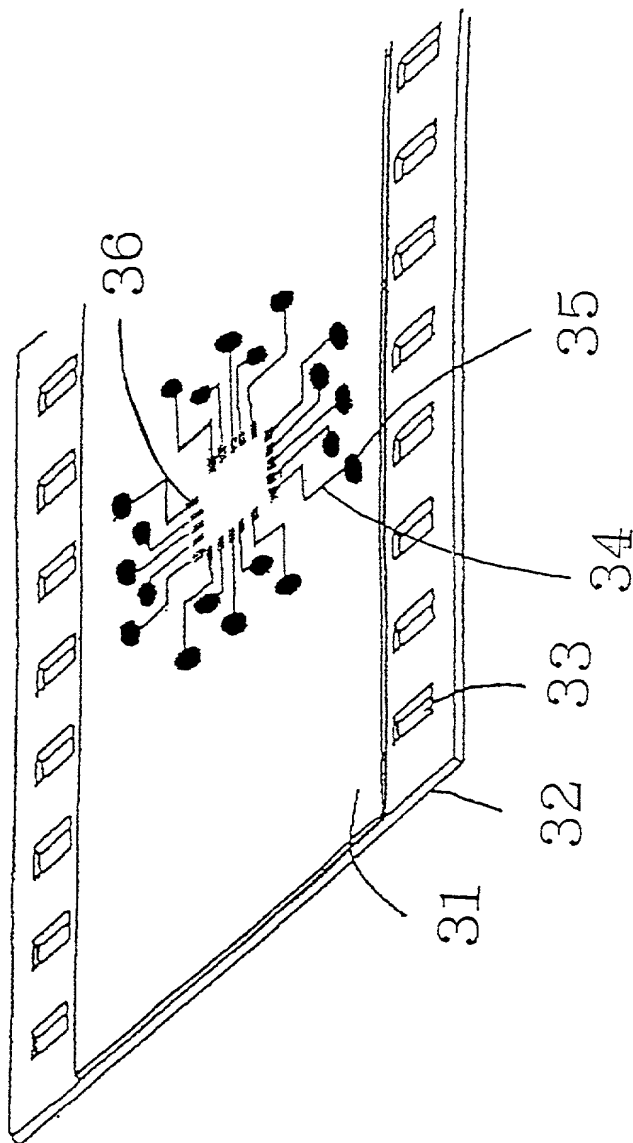


Fig. 6

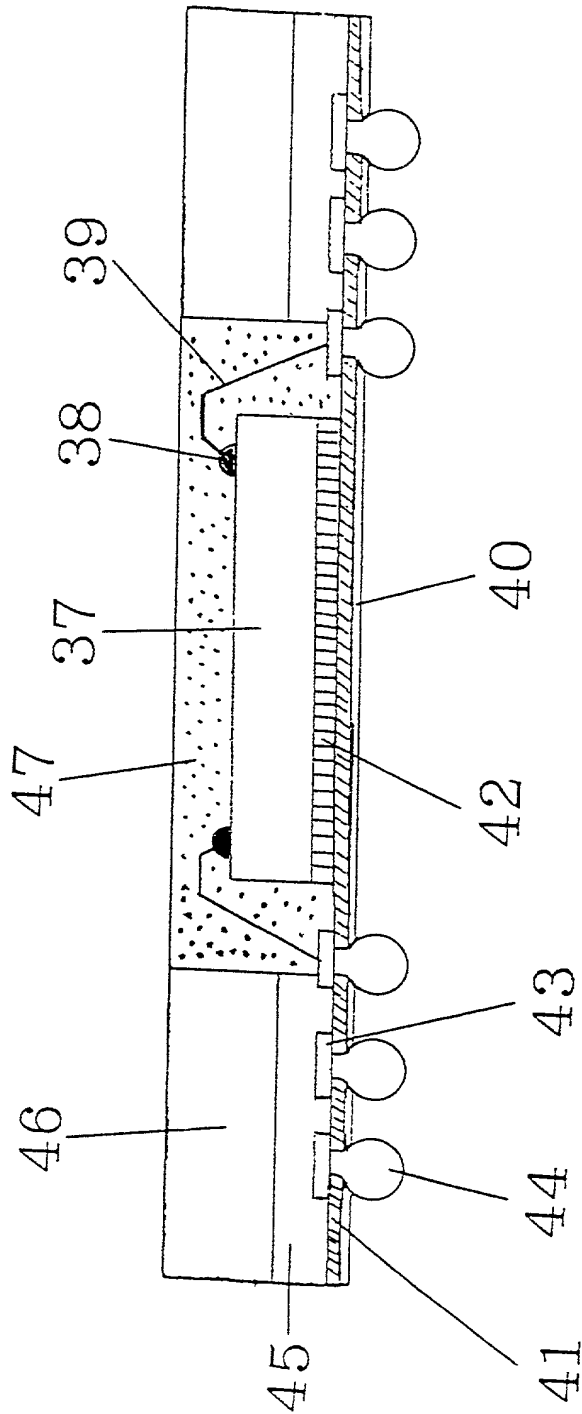
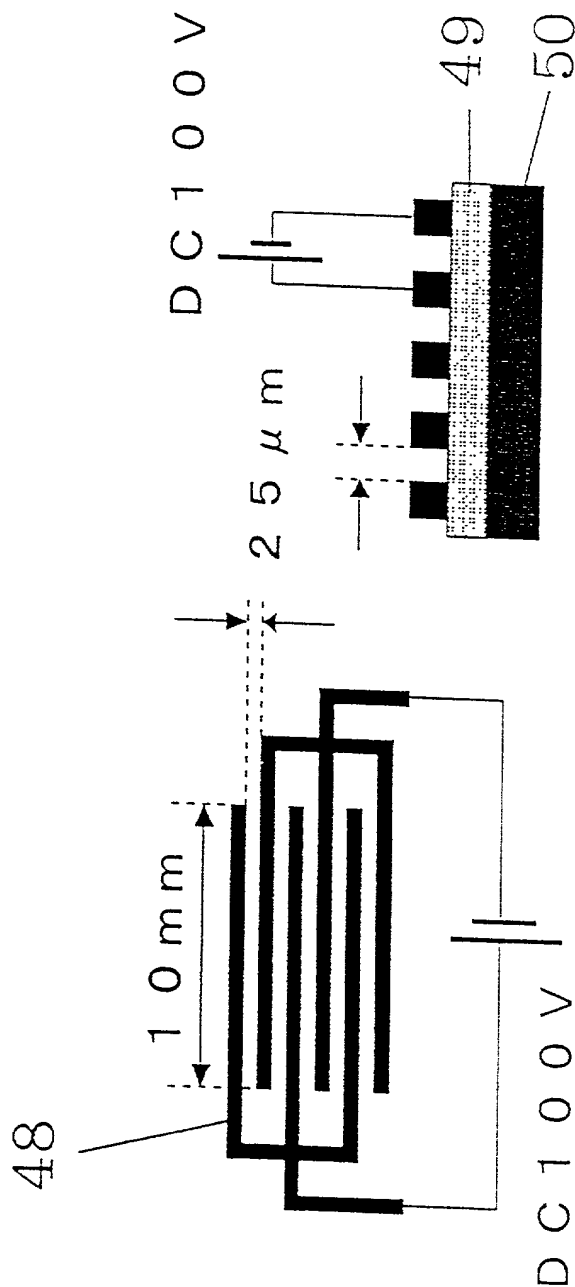
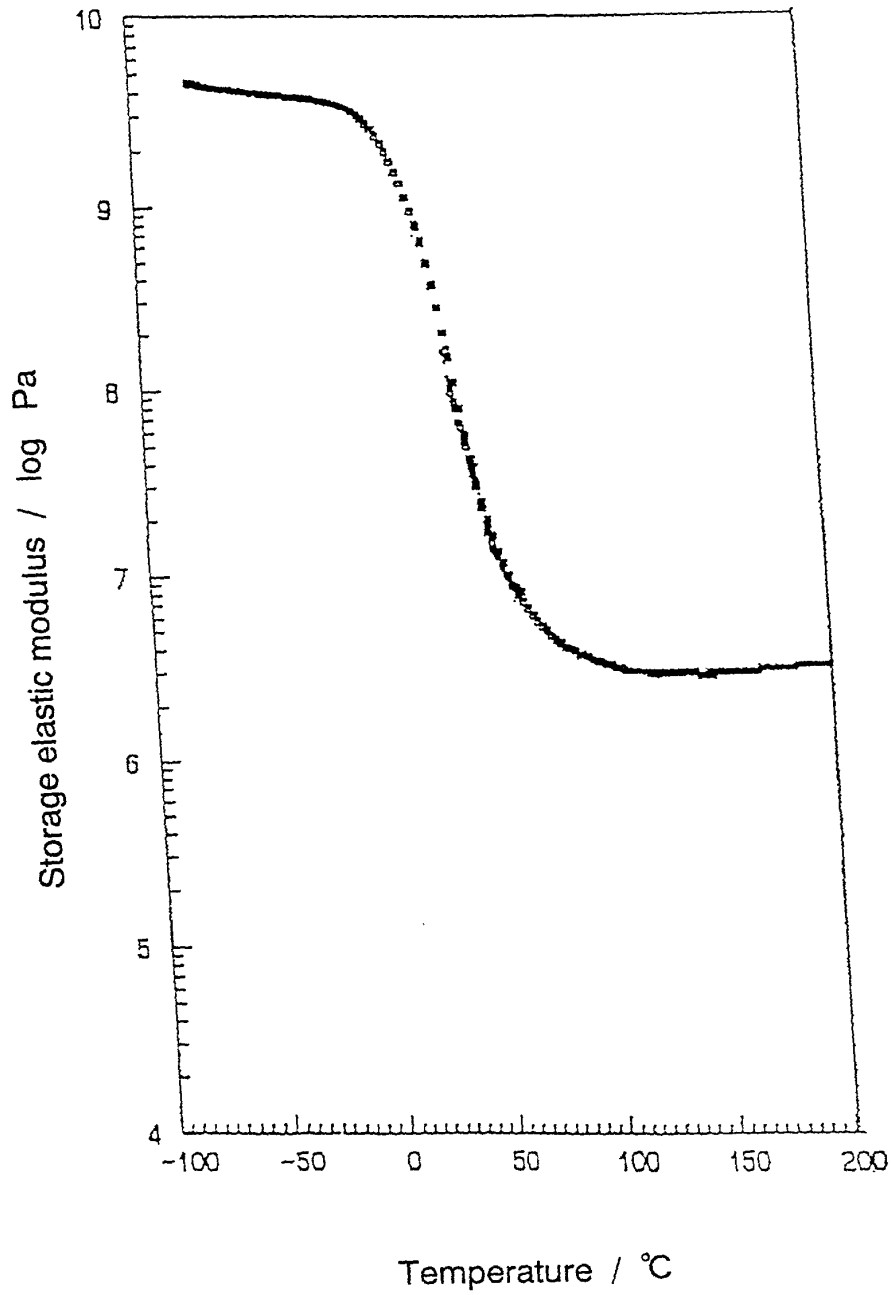


Fig. 7



*Fig. 8*



T06280" E1504660



*Fig. 9*

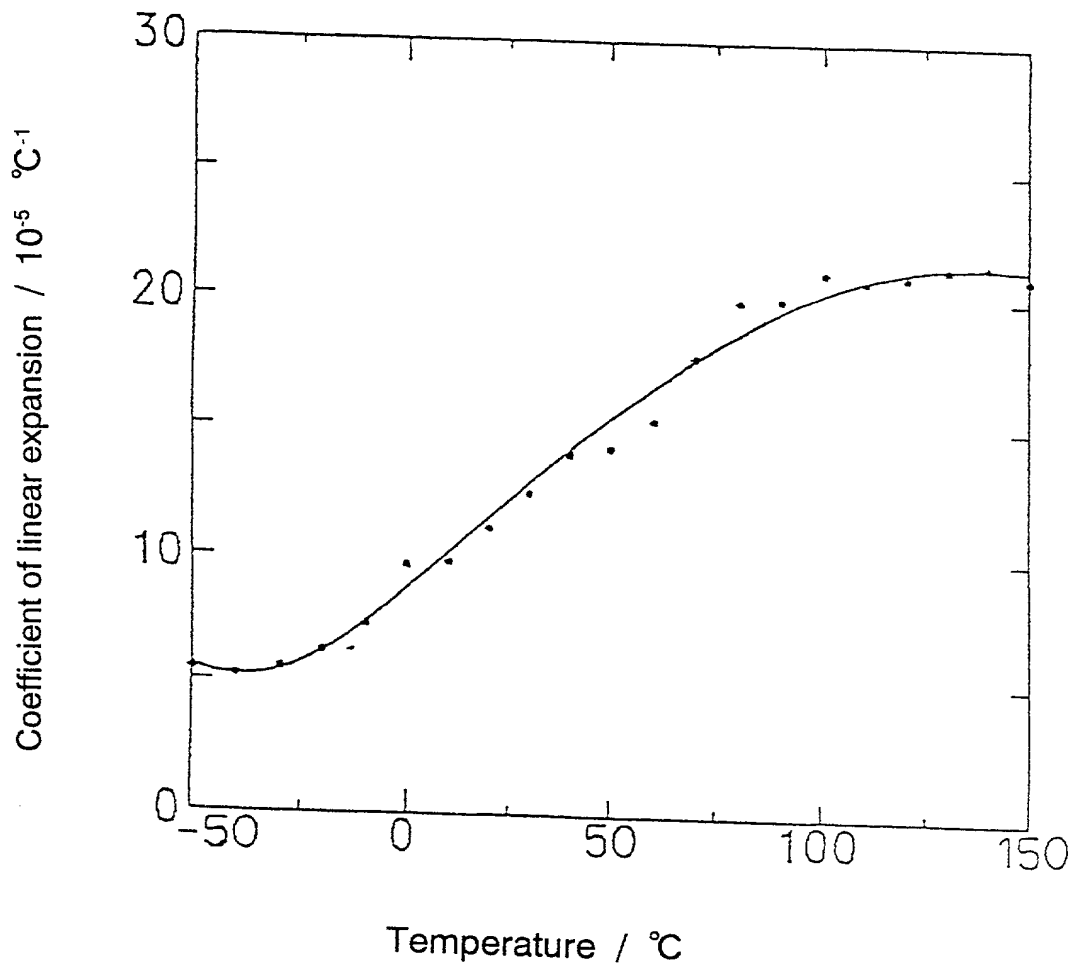


Fig. 10

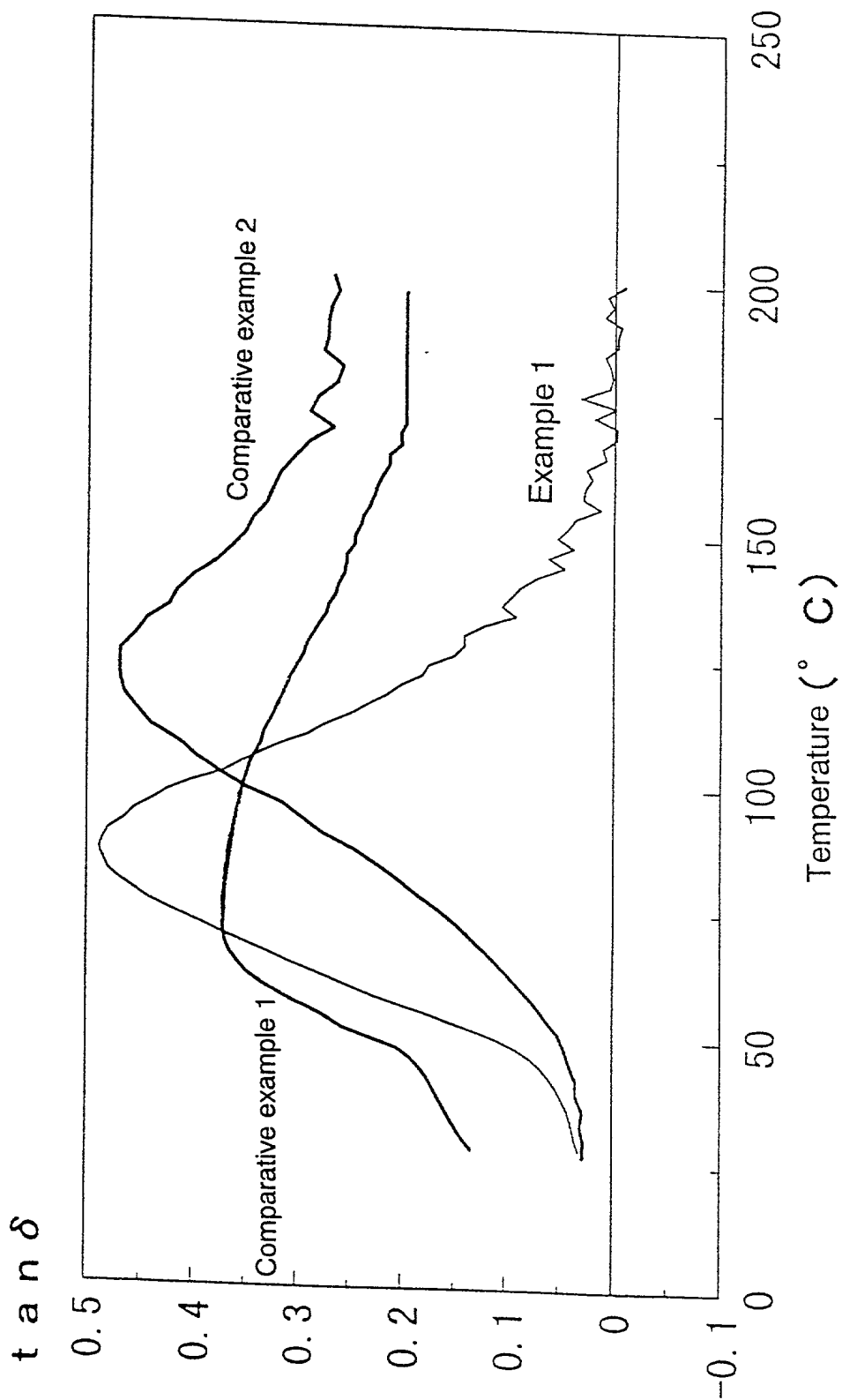


Fig. 11

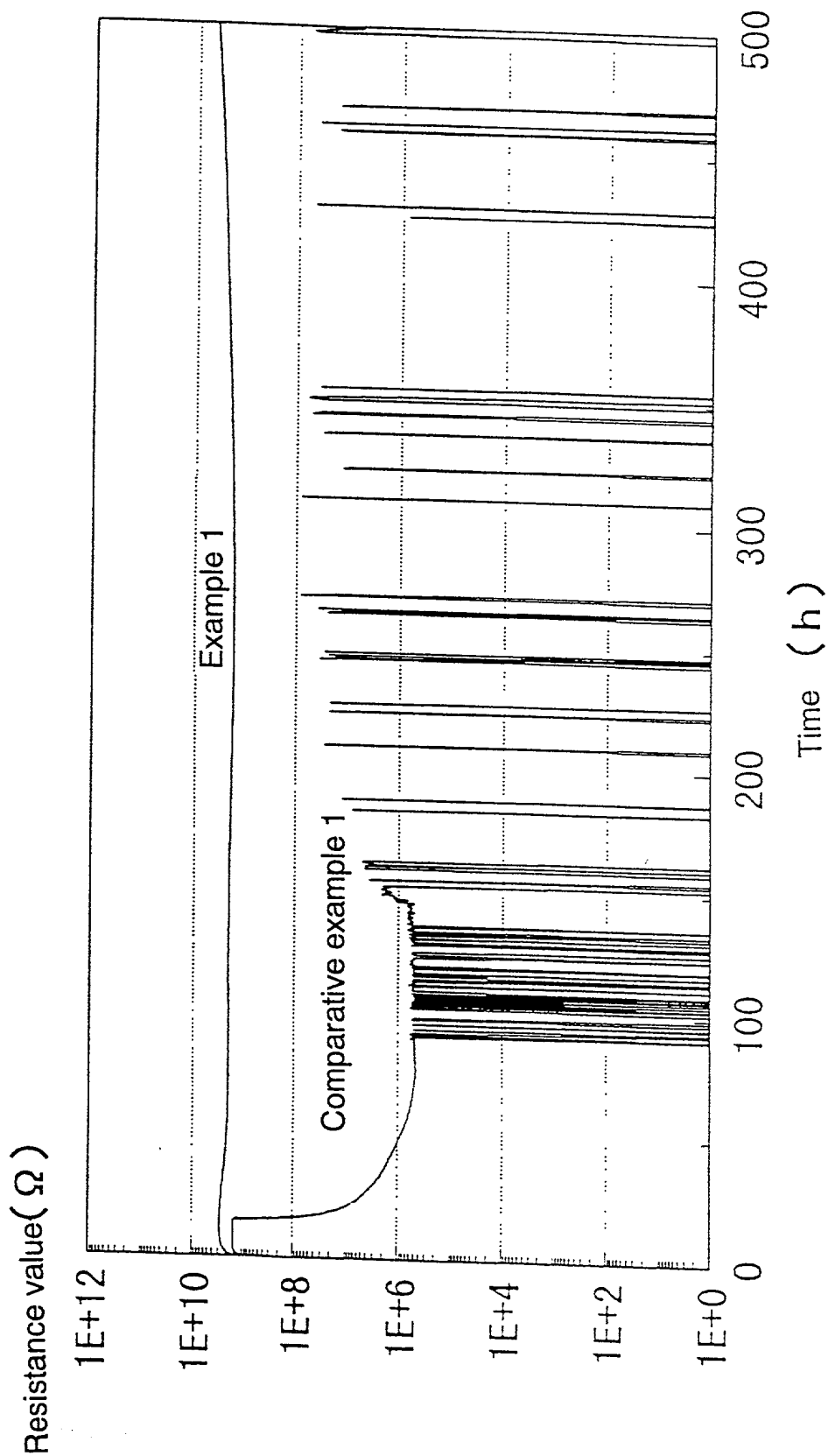


Fig. 12

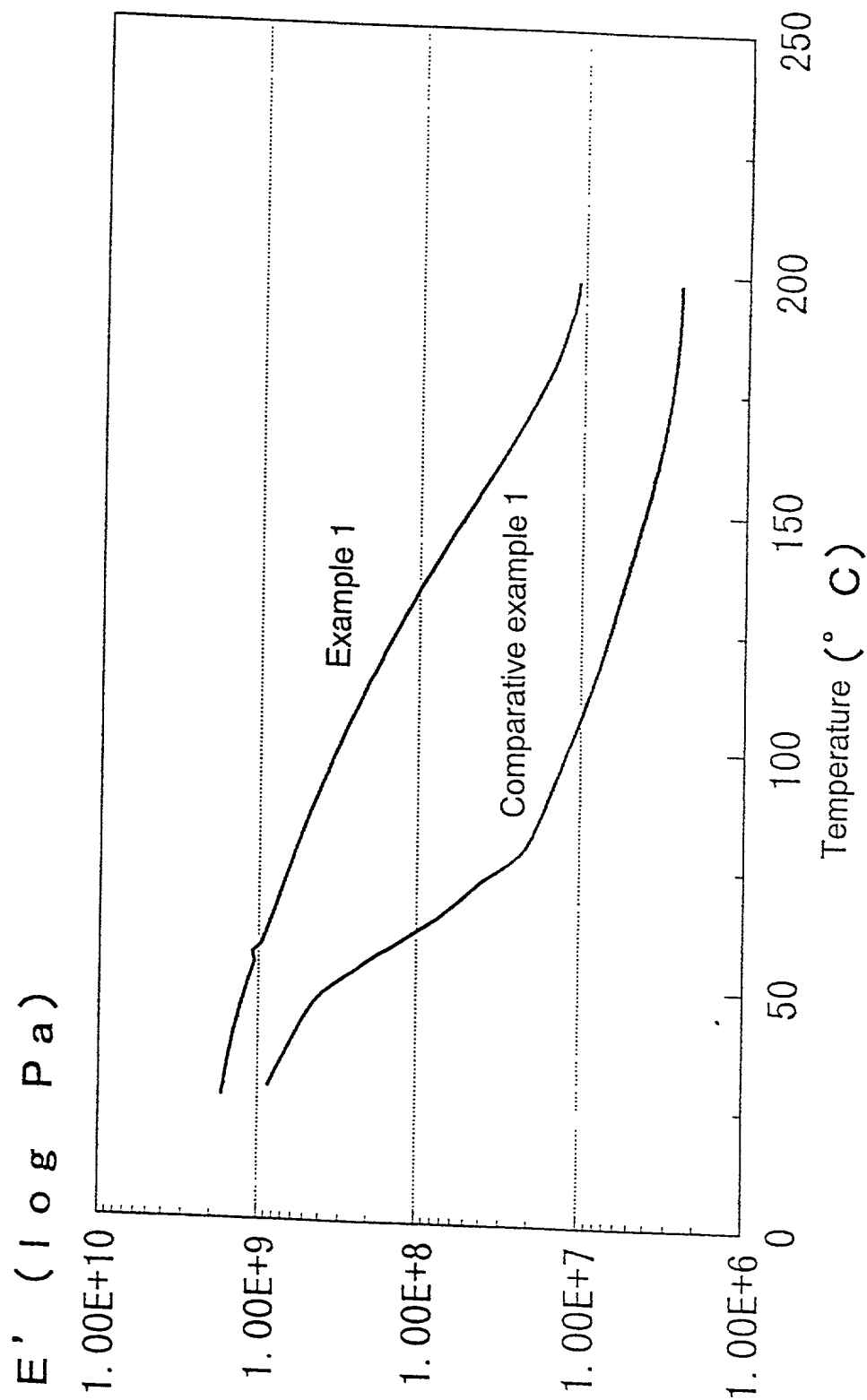


Fig. 13

